

## 600V 15A APT15D60BG

Pb Free Terminal Finish.

# **ULTRAFAST SOFT RECOVERY RECTIFIER DIODE**

#### **PRODUCT APPLICATIONS**

- Anti-Parallel Diode
   -Switchmode Power Supply
   -Inverters
- Free Wheeling Diode
   -Motor Controllers
   -Converters
   -Inverters
- Snubber Diode
- PFC

#### PRODUCT FEATURES

- Ultrafast Recovery Times
- Soft Recovery Characteristics
- Popular TO-247 Package
- Low Forward Voltage
- Low Leakage Current

### PRODUCT BENEFITS

- Low Losses
- Low Noise Switching
- Cooler Operation
- Higher Reliability Systems
- Increased System Power Density





#### **MAXIMUM RATINGS**

All Ratings:  $T_{C} = 25^{\circ}C$  unless otherwise specified.

Symbol	Characteristic / Test Conditions	APT15D60BG	UNIT
V <sub>R</sub>	Maximum D.C. Reverse Voltage		
V <sub>RRM</sub>	Maximum Peak Repetitive Reverse Voltage	600	Volts
V <sub>RWM</sub>	Maximum Working Peak Reverse Voltage		
I <sub>F(AV)</sub>	Maximum Average Forward Current ( $T_{C} = 133^{\circ}C$ , Duty Cycle = 0.5)	15	
I <sub>F(RMS)</sub>	RMS Forward Current (Square wave, 50% duty)	32	Amps
I <sub>FSM</sub>	Non-Repetitive Forward Surge Current $(T_J = 45^{\circ}C, 8.3ms)$	110	
T <sub>J</sub> ,T <sub>STG</sub>	Operating and StorageTemperature Range	-55 to 175	°C
TL	Lead Temperature for 10 Sec.	300	

#### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions		MIN	ТҮР	МАХ	UNIT
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 15A		1.6	1.8	Volts
		I <sub>F</sub> = 30A		1.9		
		I <sub>F</sub> = 15A, T <sub>J</sub> = 125°C		1.4		
I <sub>RM</sub>	Maximum Reverse Leakage Current	V <sub>R</sub> = V <sub>R</sub> Rated			150	μA
		$V_R = V_R$ Rated, $T_J = 125^{\circ}C$			500	
C <sub>T</sub>	Junction Capacitance, V <sub>R</sub> = 200V			23		pF

#### **DYNAMIC CHARACTERISTICS**

#### APT15D60BG

Symbol	Characteristic	Test Conditions	MIN	ТҮР	МАХ	UNIT
t <sub>rr</sub>	Reverse Recovery Time $I_F = 1A$ , $di_F/dt = -100A/\mu s$ , $V_R = 30V$ , $T_J = 25^{\circ}C$		-	21		
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 15A, di <sub>F</sub> /dt = -200A/μs V <sub>R</sub> = 400V, T <sub>C</sub> = 25°C	-	80		115
Q <sub>rr</sub>	Reverse Recovery Charge		-	95		nC
I <sub>RRM</sub>	Maximum Reverse Recovery Current		-	3	-	Amps
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 15A, di <sub>F</sub> /dt = -200A/μs V <sub>R</sub> = 400V, T <sub>C</sub> = 125°C	-	150		ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	520		nC
I <sub>RRM</sub>	Maximum Reverse Recovery Current		-	7	-	Amps
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 15A, di <sub>F</sub> /dt = -1000A/µs V <sub>R</sub> = 400V, T <sub>C</sub> = 125°C	-	60		ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	810		nC
IRRM	Maximum Reverse Recovery Current		-	22		Amps

#### THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	ТҮР	MAX	UNIT
R <sub>eJC</sub>	Junction-to-Case Thermal Resistance			1.35	°C/W
R <sub>0JA</sub>	Junction-to-Ambient Thermal Resistance			40	
W <sub>T</sub>	Package Weight		0.22		oz
			5.9		g
Torque	Maximum Mounting Torque			10	lb∙in
				1.1	N∙m

APT Reserves the right to change, without notice, the specifications and information contained herein.







FIGURE 1b, TRANSIENT THERMAL IMPEDANCE MODEL





0.25 I<sub>RRM</sub>

5

3

2



- 2 di<sub>F</sub>/dt Rate of Diode Current Change Through Zero Crossing.
- 3 I<sub>BBM</sub> Maximum Reverse Recovery Current.
  - t<sub>rr</sub> Reverse Recovery Time, measured from zero crossing where diode current goes from positive to negative, to the point at which the straight line through I<sub>RRM</sub> and 0.25•I<sub>RRM</sub> passes through zero.
- 5 Q<sub>rr</sub> Area Under the Curve Defined by I<sub>RRM</sub> and t<sub>rr</sub>.

Figure 10, Diode Reverse Recovery Waveform and Definitions

Zero



#### **TO-247 Package Outline**



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